

L1 ANSWER 1 OF 1 WPIX COPYRIGHT 2003 THOMSON DERWENT on STN

AN 1986-014605 [03] WPIX

DNC C1986-005995

TI Low-pressure plasma working appts. - with individual chambers to evacuate, work and return to normal pressure the workpieces.

DC M13

IN BELL, G

PA (BMPP-N) BMP PLASMATECH

CYC 1

PI DE 3415012 A 19860109 (198603)* 9p <--

DE 3415012 C 19880616 (198824) <--

ADT DE 3415012 A DE 1984-3415012 19840419; DE 3415012 C DE 1984-3415012 19840419

PRAI DE 1984-3415012 19840419

IC B01J019-08; C23C014-34

AB DE 3415012 A UPAB: 19930922

Substrates are worked with a low pressure plasma by feeding them continually into a vacuum antichamber having an entrance and joining path to the process chamber. This chamber is sealed and the vacuum required is produced. The entrance to the process chamber is opened and the substrates passed to this chamber already under vacuum. A third exit chamber is evacuated and after the process is completed is opened to the process chamber from when the substrates are delivered. When the substrates are sealed in the exit chamber the atmosphere is returned to normal pressure before the substrates are removed.

ADVANTAGE - Enables a continuous process with reproducible process conditions.

O/I

FS CPI

FA AB

MC CPI: M13-E05